

描述 / Descriptions

8.0A 单相硅桥整流器，反向电压：50~1000V，GBU 封装。

8.0A Single-Phase Silicon Bridge Rectifier, Reverse Voltage:50~1000V,GBU package.

特征 / Features

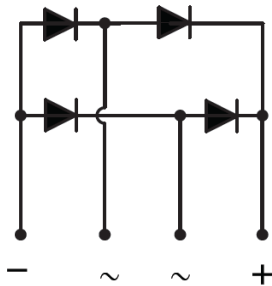
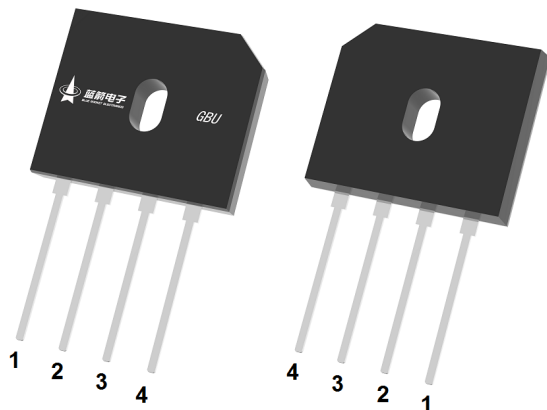
优化 PCB 板选择，塑料模具外壳，塑料的 UL 易燃性等级为 94V-0，无卤产品。

Ideal for printed circuit board, Case material molded plastic, The plastic material has U/L flammability classification 94V-0, HF Product.

用途 / Applications

一般用途。

General purpose.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

PIN1 : DC-

PIN2 : AC

PIN 3 : AC

PIN 4 : DC+

印章代码 / Marking

见印章说明。

See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		GBU 8005	GBU 801	GBU 802	GBU 804	GBU 806	GBU 808	GBU 810	
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified output current at T _C =100°C(with heatsink)	I _{F(AV)}	8.0							A
Peak forward surge current single sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	175							A
Rating for fusing (t<8.3ms)	I ² t	127							A ² s
Operating Temperature Range	T _J	-55 to +150							°C
Storage Temperature Range	T _{stg}	-55 to +150							°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Maximum Forward Voltage	V _F	I _F =4.0A	1.1	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I _R	T _a =25°C	10	μA
		T _a =125°C	500	

电参数曲线图 / Electrical Characteristic Curve

Fig. 1 Derating Curve for Output Rectified Current

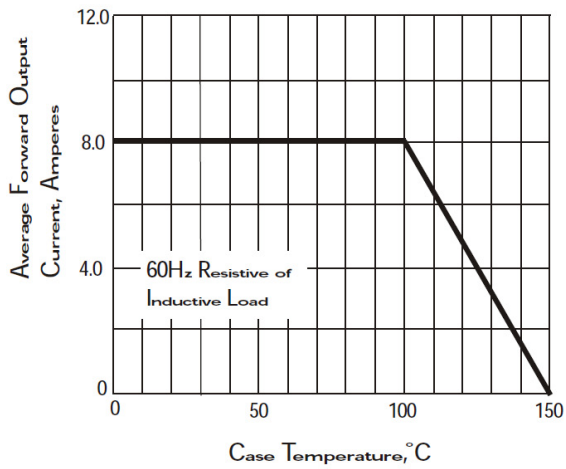


Fig. 2 Maximum Non-repetitive Peak Forward Surge Current

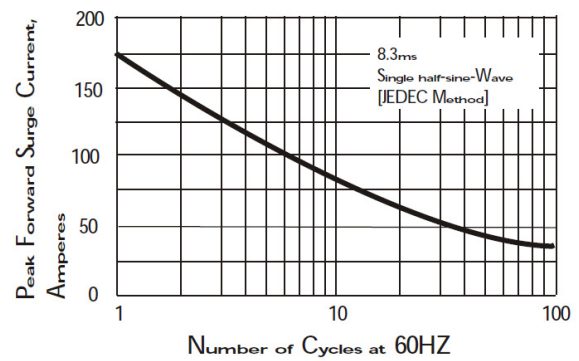


Fig. 3 Typical Instantaneous Forward Characteristics

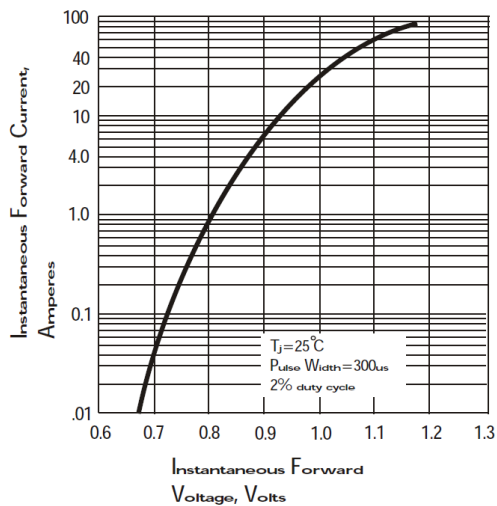


Fig. 4 Typical Reverse Characteristics

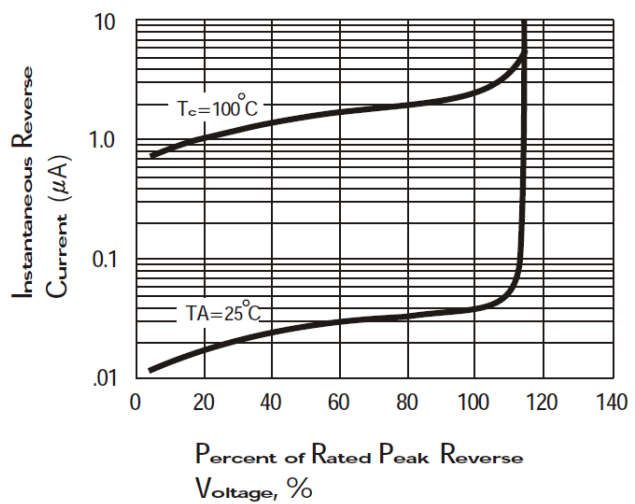
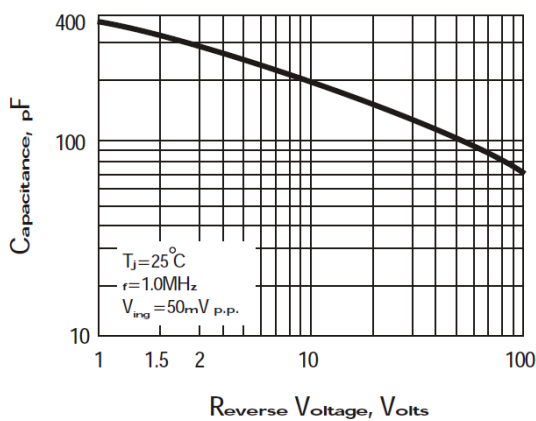
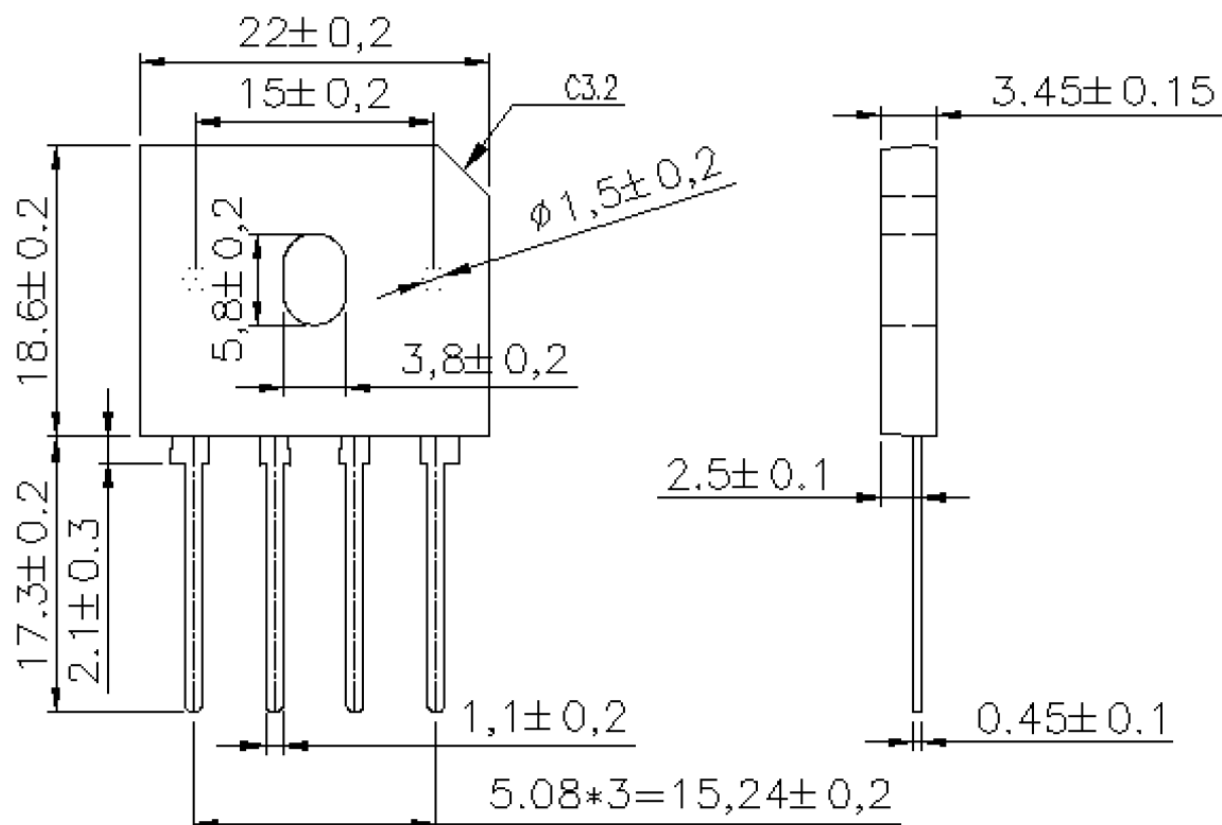


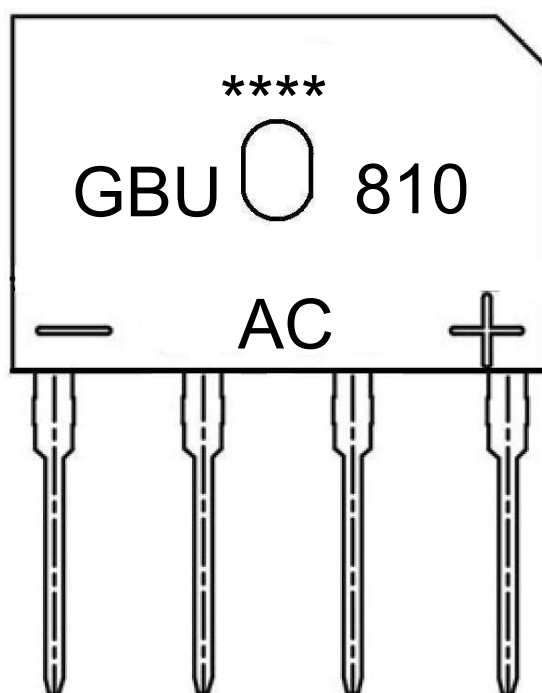
Fig. 5 Typical Junction Capacitance



外形尺寸图 / Package Dimensions



印章说明 / Marking Instructions



说明：

****： 为生产批号代码，随生产批号变化

GBU810： 为产品型号

- AC +： 引脚功能

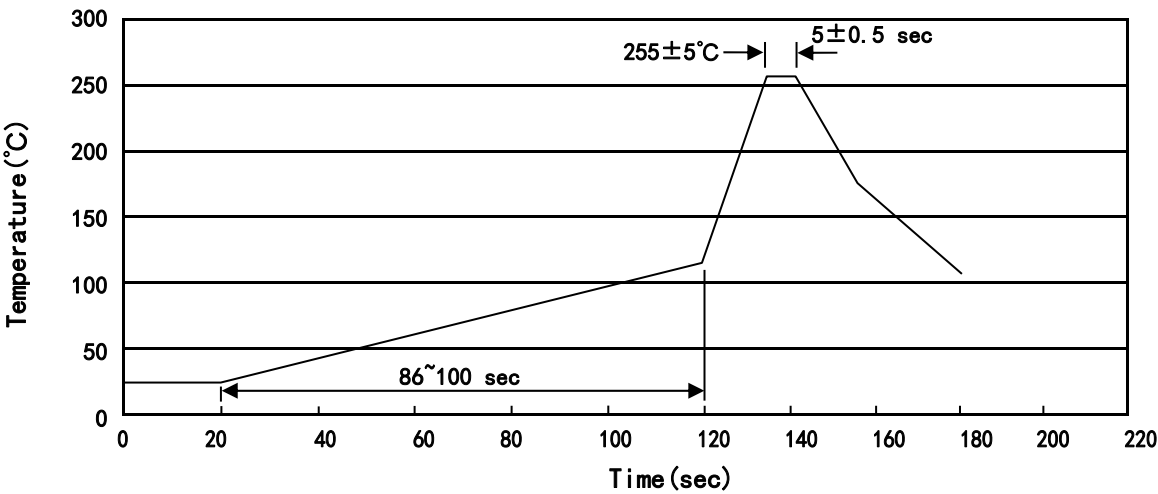
Note:

****: Lot No. Code, code change with Lot No

GBU810: Product Type

- AC +: Pin function

波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：270±5°C 时间：10±1 sec. Temp.:270±5°C Time:10±1 sec

包装规格 / Packaging SPEC.

散件包装 / BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 盒	Outer Box 箱
GBU	-	-	250	10	2500	-	-	-

使用说明 / Notices